

ABSTRACT OF THE DISCLOSURE

An apparatus for treating wafer-shaped articles includes at least one linear arranged array of a plurality of at least two process units wherein in each such process unit one single wafer-shaped article can be treated, a cassette-holding unit for holding at least one cassette storing at least one wafer-shaped article therein and a transport system for picking a wafer-shaped article from a cassette and placing it into one of a process unit. The apparatus has a transport unit movably mounted on a linear track. The transport unit includes at least one holding member for holding a single wafer-shaped article in a substantially vertical plane parallel to the linear track.